

1 1

1 2

サンプル	研磨レート (A/min)	均一性 (%)	平坦化特性 0-加段差(A)	底部削れ量(A)	耐久性
実施例1	900	3	60	900	1000枚
実施例2	850	6	40	750	2500枚
実施例3	870	4.5	50	800	1100枚
実施例4	920	4.5	50	800	950枚
実施例5	900	3	60	900	1000枚
実施例6	850	3	60	900	1000枚
比較例1	840	11	70	1050	4000枚
比較例2	930	3	30	700	300枚
比較例3	870	12	40	750	1100枚
比較例4	700	3	60	900	1100枚

【0025】

10*【図1】本発明の研磨パッドの断面図である

【発明の効果】本発明の研磨パッドを各種の研磨に用いることにより、高い研磨速度を維持しながら、平坦性、均一性共に優れた被研磨物を得ることが出来る。

【符号の説明】

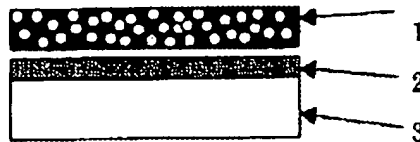
1：表面研磨層（発泡ポリウレタン）

2：高弾性層（PET、発泡PET層）

* 3：柔らかい層

【図面の簡単な説明】

【図1】



フロントページの続き

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PAT-NO: JP02002075933A
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TITLE: POLISHING PAD
PUBN-DATE: March 15, 2002

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APPL-NO: JP2000252832

APPL-DATE: August 23, 2000

INT-CL (IPC): H01L021/304, B24B037/00

ABSTRACT:

PROBLEM TO BE SOLVED: To provide a polishing pad for polishing semiconductor wafer capable of meeting conflict requirement of uniformity of polishing degree all over the wafer and planarization characteristic of concavity and convexity of micro region in the polishing process for planarizing concavity and convexity of micro pattern formed on the semiconductor wafer.

SOLUTION: The polishing pad for polishing semiconductor wafer with patterns formed on its surface and having micro concavity and convexity comprises a polishing layer 1 of the pad with its most surface layer formed by porous elastic resin layer, a resin layer 2 (second layer) adjoining the

porous
elastic resin layer and having greater degree of elasticity than the
same, and
a layer 3 (third layer) laminated on the opposite side of the porous
elastic
resin layer from the second layer and softer enough than the second
layer.

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TITLE: Polishing pad for semiconductor wafer, has
soft layer with elasticity lower than PET layer, which is
laminated on reverse side of PET layer

PATENT-ASSIGNEE: TOYOCO KK[TOYM]

PRIORITY-DATA: 2000JP-0252832 (August 23, 2000)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE
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BASIC-ABSTRACT:

NOVELTY - A foam PET layer (2) with elasticity higher than a polish layer (1) having a foam polyurethane, is formed on the polish layer. A soft layer (3) with elasticity lower than the PET layer, is laminated on the reverse side of the PET layer.

USE - Used for polishing semiconductor wafer.

ADVANTAGE - Maintains high polishing velocity, by using the polishing pad for various polishing. Uniform polishing is enhanced.

DESCRIPTION OF DRAWING(S) - The figure shows the sectional view of the polishing pad.

Polish layer 1

Foam PET layer 2

Soft layer 3

CHOSEN-DRAWING: Dwg.1/1

TITLE-TERMS: POLISH PAD SEMICONDUCTOR WAFER SOFT LAYER ELASTIC LOWER PET LAYER

LAMINATE REVERSE SIDE PET LAYER

DERWENT-CLASS: A85 L03 P61 U11

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